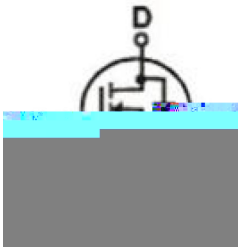

A 202

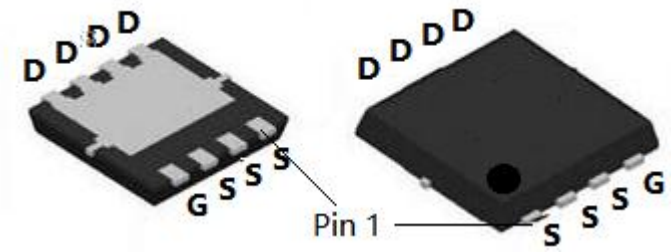
PDFN5×6 N 。
N-Channel MOSFET in a PDFN5×6 Plastic Package .

Low $R_{DS(ON)}$ to minimize conductive loss;low Gate Charge for fast switching;Low Thermal resistance;HF Product.

MB/NB/UMPC/VGA Buck -

Battery Management,High Frequency Point-of-Load Synchronous Buck Conventer for MB/NB/UMPC/VGA,Networking DC-DC Power System,Load Switch.





PIN1 2 3 S PIN4 G PIN5 6 7 8 D

See Marking Instructions.

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Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	100	V
Drain Current - Continuous	I_D	168	A
Drain Current – Pulsed	I_{DM}	400	A
Gate-Source Voltage	V_{GS}	±20	V
Power Dissipation	$P_D(T_c=25℃)$	215	W
Single Pulse Avalanche Energy(L=0.5mH)	E_{AS}	563	mJ
Avalanche Current(L=0.5mH)	I_{AS}	37.5	A
Junction and Storage Temperature Range	T_j, T_{stg}	-55 to 150	℃
Thermal resistance, junction - ambient t ≤ 10s	$R_{\theta JA}$		

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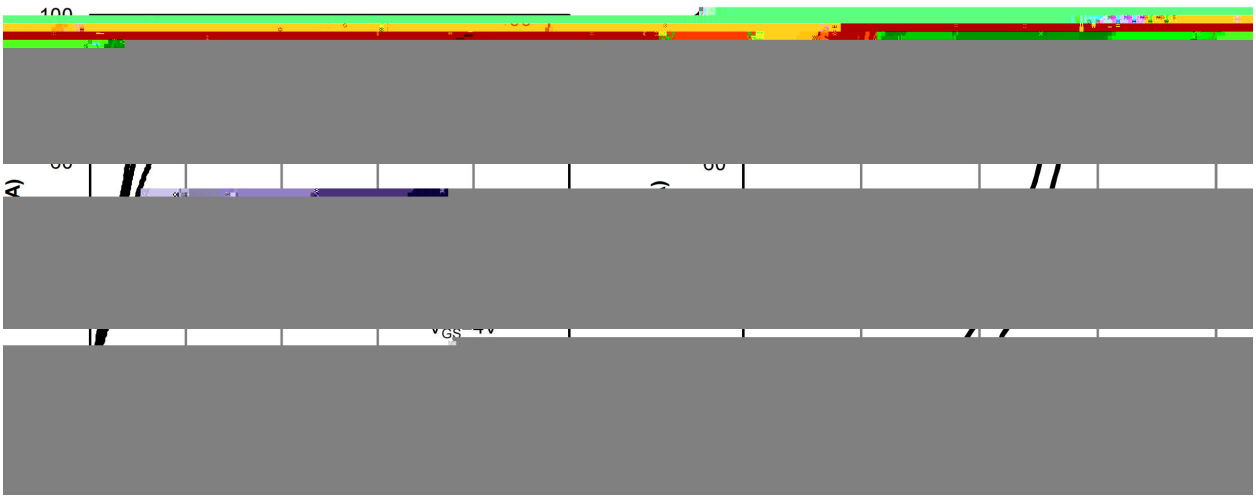
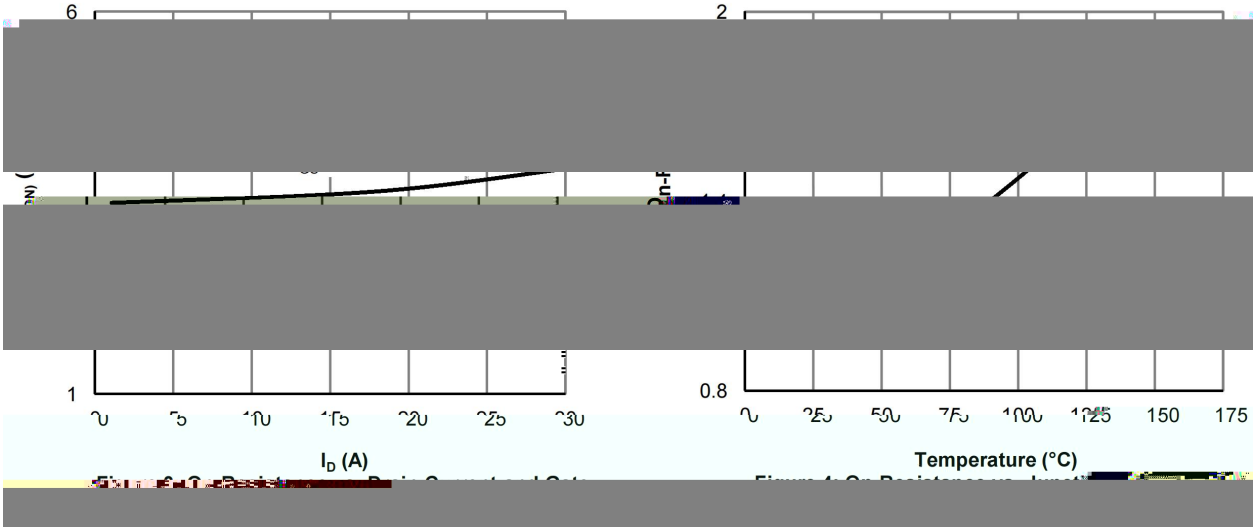
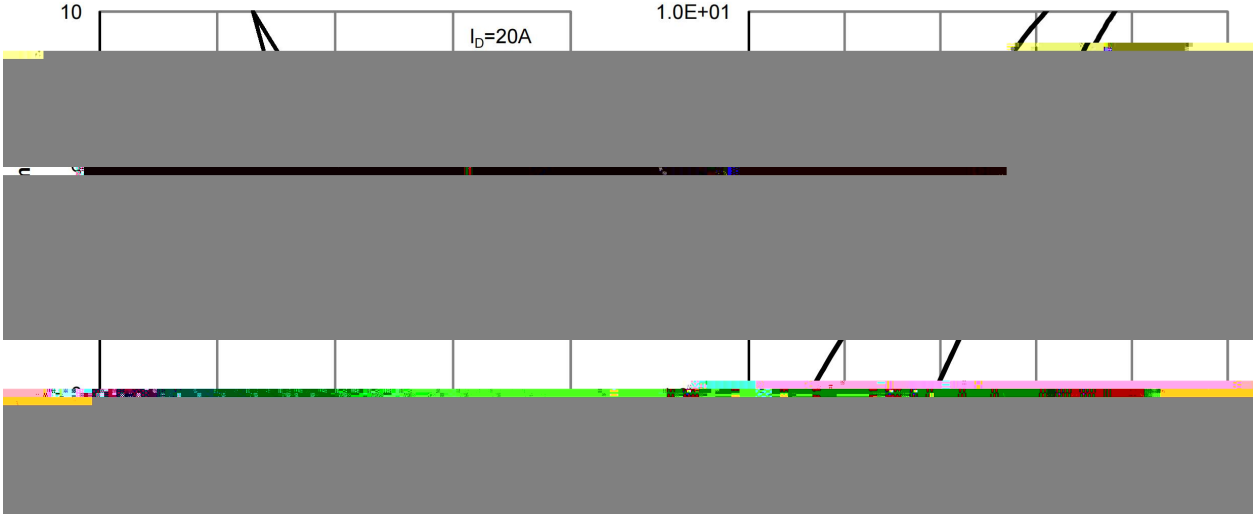
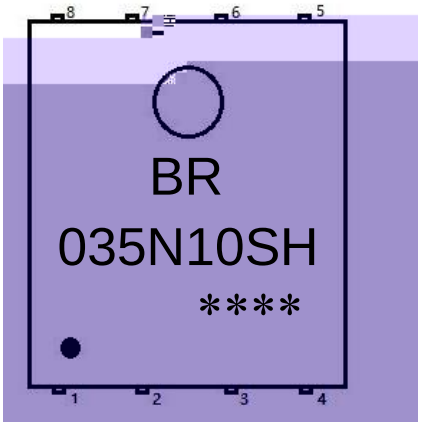
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=10V V_{DS}=50V R_L=2.5Ω R_{GEN}=3Ω				




6
1
I_D (A)
2
0.8
Temperature (°C)
150
175


10
I_D=20A
1.0E+01



BR

035N10SH

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Note

BR	Company Code
035N10SH	Product Type
****:	Lot No. Code, code change with Lot No

Temperature Profile for IR Reflow Soldering(Pb-Free)

				Note:
1	150	180	60 90sec;	1.Preheating:150~180℃, Time:60~90sec.
2	245±5		5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3		2	10℃/sec.	3. Cooling Speed: 2~10℃/sec.

260±5℃	10±1 sec.

Temp.:260±5℃	Time:10±1 sec